Title of Your Project

Project progress report submitted

to

## MANIPAL ACADEMY OF HIGHER EDUCATION

For Partial Fulfillment of the Requirement for the

Award of the Degree

of

Bachelor of Technology

in

Computer and Communication Engineering

by

Your Name

Reg. No. 210953xxx

Under the guidance of

Dr.XYZ (Name of Internal Guides)

Designation of Internal Guides

Department of I & CT

Project Group Name/

March 2024

**1. Introduction**

Give general introduction about your research work.

**2. Literature Survey**

**Give the comprehensive literature on different component used /features used .If used in any other applications how is it used there and why you are using it in the present application?**

//To provide a comprehensive overview of the various components and features used in the literature

//Qualitative comparison of existing literature with proposed work

//Give about 8 to 10 related works here [1][2][3].

**3. Problem Definition**

Define your research problem.

**4. Objective**

List main objectives of your research work

**5. Methodology**

The work should include methodology along with the Architecture diagram to depict the entire workflow. Additionally, include Low level Design(LLD) and High level Design(HLD).

Give a diagram, flow chart, indicating various modules of your work.

**6 Workdone So Far**

This section includes all those modules along with the results which have been completed.

**7 Remaining Work**

In this section list the remaining work.

**8 Scope**

Who will benefit from your research work?

References

[1] M. Shell. (2007) IEEEtran webpage on CTAN. [Online]. Available:

http://www.ctan.org/tex-archive/macros/latex/contrib/IEEEtran/

[2] Y. Okada, K. Dejima, and T. Ohishi, “Analysis and comparison of PM synchronous

motor and induction motor type magnetic bearings,” IEEE Trans. on EE, vol. 31,

pp. 1047–1053, Sep./Oct. 1995.

[3] R. K. Gupta and S. D. Senturia, “Pull-in time dynamics as a measure of absolute

pressure,” in Proc. IEEE International Workshop on Microelectromechanical Systems

(MEMS’97), Nagoya, Japan, Jan. 1997, pp. 290–294.